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Conductive and dielectric resin foaming particles - are
coated with emulsion, spread with conductive material and dielectric
material and then dried, used for conductive cushioning materials

Patent Assignee: KANEKA CORP (KANF)

Number of Countries: 001 Number of Patents: 001

Patent Family:

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JP 4356543	A	19921210	JP 91142390	A	19910517	199304 B

Priority Applications (No Type Date): JP 91142390 A 19910517

Patent Details:

Patent No	Kind	Lan	Pg	Main IPC	Filing Notes
JP 4356543	A		5	C08J-009/22	

Abstract (Basic): JP 4356543 A

Conductive and dielectric thermoplastic resin foaming particles are claimed, the surfaces of which are coated with an emulsion and then spread with a conductive material and a dielectric material and dried to give conductive and dielectric thermoplastic resin foaming particles. The particles are put in a mould, heated and expanded to give a conductive and dielectric thermoplastic resin foam.

Pref. the conductive material is graphite powder, carbon black or their mixt. The dielectric material is Rochelle salt. The spread of the dielectric material on the particles is more than 7 g/m². The spread of the conductive material on the particles is more than 1 g/m². The emulsion is a polymer emulsion. The resin foam has a surface resistance and a vol. resistance of less than 10 power (4) Ohm, a specific inductive capacity of more than 7 and dielectric loss of more than 0.4.

Pref. the thermoplastic resin prefoamed fine particles are e.g. polystyrene prefoamed particles with an expansion ratio of 5,000%. The polymer emulsion is e.g. a styrene-acrylic resin emulsion.

USE/ADVANTAGE - For a conductive cushioning material and electromagnetic wave absorbing material. They have a high conductivity and dielectric

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Title Terms: CONDUCTING; DIELECTRIC; RESIN; FOAM; PARTICLE; COATING;
EMULSION; SPREAD; CONDUCTING; MATERIAL; DIELECTRIC; MATERIAL; DRY;
CONDUCTING; CUSHION; MATERIAL

Derwent Class: A32; A85; L03

International Patent Class (Main): C08J-009/22

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B29K-105-16

File Segment: CPI

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A12-B07B; A12-E01; A12-S04; L03-A02A; L03-GPlasdoc Codes (KS): 0229 0304 0306 0488 2386 2430 2482 2499 2504 2536 2540
2541 2549 2551 2555 2617 2726 2743

Polymer Fragment Codes (PF):

001 014 03- 034 055 056 074 081 27& 393 397 402 408 409 431 436 443
466 472 477 491 50- 506 507 509 551 556 623 627 688 694 722

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